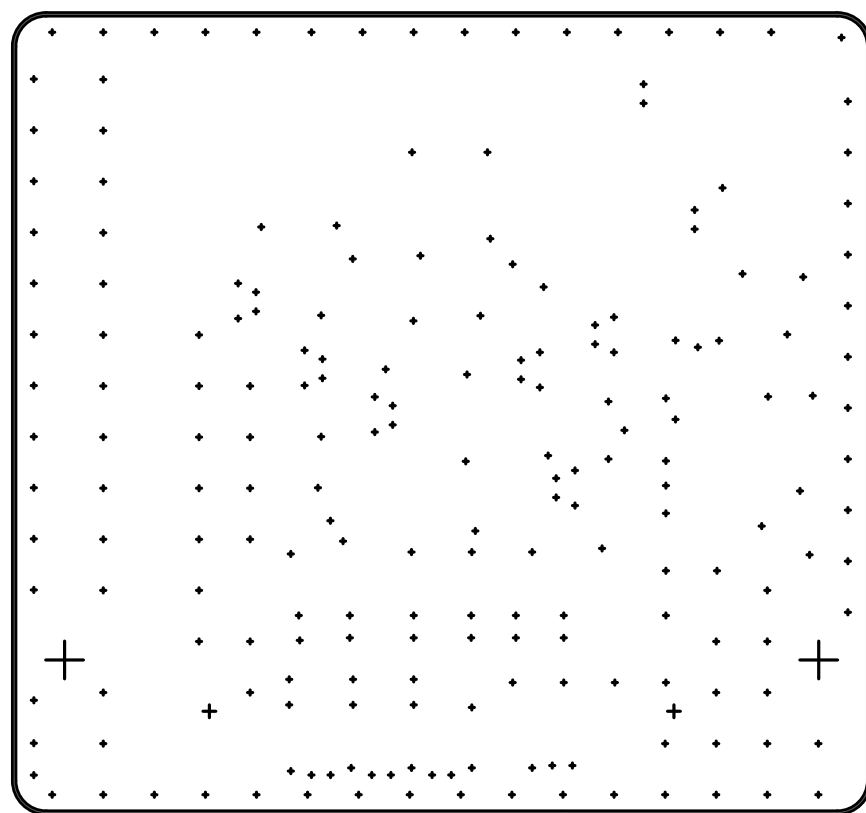


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	7628*1	0.210mm	4.05	
2	L02_GND	CF-004	0.015mm		
	Dielectric 2	Core	0.400mm	4.05	
3	L03_GND	CF-004	0.015mm		
	Dielectric 3	7628*1	0.210mm	4.05	
4	Bottom Layer	CF-004	0.035mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 0.970mm

LAYER	IMPEDANCE		WIDTH	SPACE
	SINGLE END	DIFF		
L1 & L4	-----	100 OHM	7.55 MILS	7.0 MILS

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
A	205	0.203mm (8.00mil)	PTH	Round	Top Layer - Bottom Layer	Via
B	2	1.020mm (40.16mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
C	2	3.000mm (118.11mil)	NPTH	Round	Top Layer - Bottom Layer	Pad
	209 Total					



BOARD OUTLINE